

## Drill Legend

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
0	776	0,300mm (11,81mil)	PTH	Round	L1_Top - L14_Bot	Via	Rounded	v80h30m0mx0
X	2	0,800mm (31,50mil)	PTH	Round	L1_Top - L14_Bot	Pad	(Mixed)	(Mixed)
$\nabla$	32	0,850mm (33,47mil)	PTH	Round	L1_Top - L14_Bot	Pad	(Mixed)	(Mixed)
	10	0,900mm (35,43mil)	NPTH	Round	L1_Top - L14_Bot	Pad	Rounded	c0hn90m-1p-1
	8	1,100mm (43,31mil)	PTH	Round	L1_Top - L14_Bot	Pad	(Mixed)	(Mixed)
0	97	1,100mm (43,31mil)	PTH	Round	L1_Top - L14_Bot	Pad	(Mixed)	(Mixed)
×	7	1,600mm (62,99mil)	PTH	Round	L1_Top - L14_Bot	Pad	Rounded	c220h160m220p220
$\Diamond$	4	3,200mm (125,98mil)	NPTH	Round	L1_Top - L14_Bot	Pad	Rounded	c0hn320m-1p-1
\$	4	5,360mm (211,02mil)	PTH	Round	L1_Top - L14_Bot	Pad	Rounded	c792h536m792p792
	940 Total							

Layer Stack Up Detail for: Learning Platform for Switching Regulators [No Variations]							
Layer Name	Gerber Document	Copper Thickness	Dielectric Height	Dielectric Material			
Top Overlay	(.GTO)						
Top Solder	(.GTS)						
L1_Top	(.GTL)	0.035mm	4.0	ED 4			
L2_Bot	(.GBL)	0.035mm	1.6mm	FR-4			
Bottom Solder	(.GBS)						
Bottom Overlay	(.GBO)						

MATERIAL SPECIFICATION										
SINGLESIDED DOUBLESIDED -MULTILAYER										
MATERIAL	IATERIAL FR4 TG130 🗕									
RoHS conform YES										
PCB THICKNESS mm										
	COPPER THICKNESS 9 18 35									
AFTER PLATING um										
THROUGH PLATED BOARD YES										
SOLDER	RED	T	OP	YES	<del>-NO</del>					
MASK	RED	BOT		YES	<del>-N0</del>					
SILK-	WHITE	TOP		YES	<del>-NO</del>					
SCREEN	WHITE	В	TC	YES	<del>- NO</del>					
TEST	ELEC	YES	<del>-NO</del>							
ILOI	Α	YES	<del>-NO</del>							

TECHNOLOGY
TRACK WIDTH: 0.20r
CLEARANCE: 0.20r
ANNULAR RING: 0.25r
HOLE SIZE: 0.300



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1 2 3 7 8